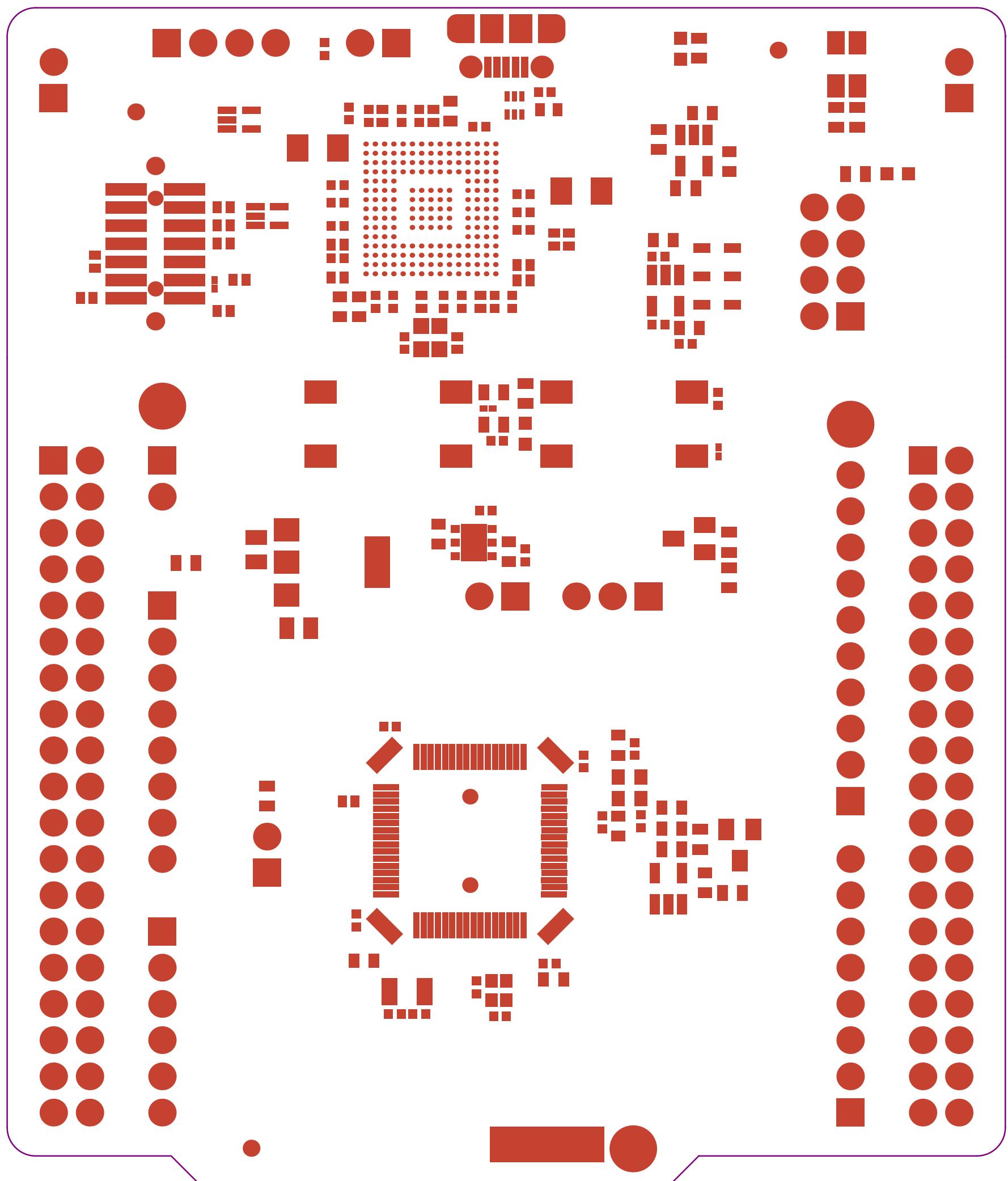


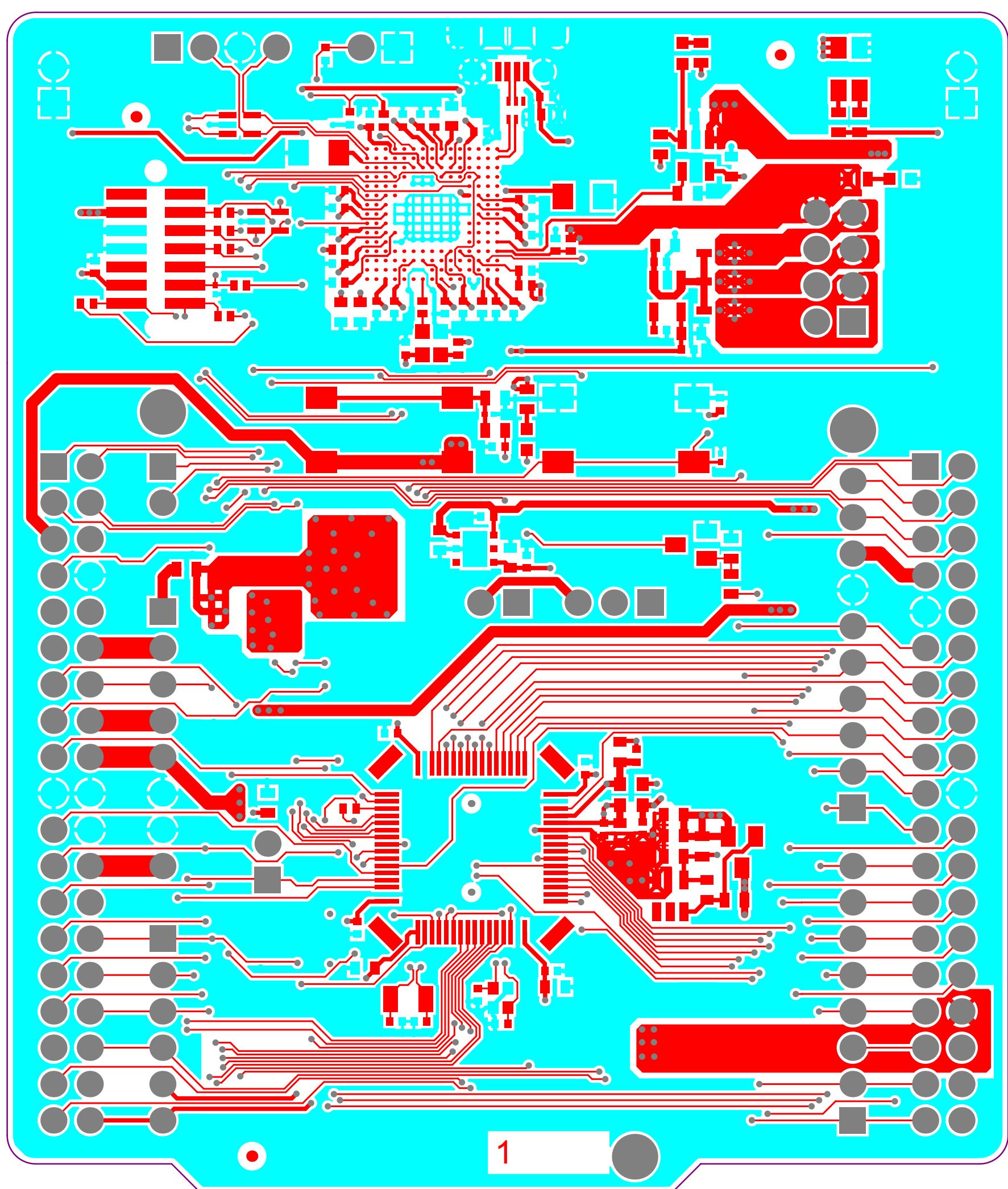
Top Overlay

.GBO



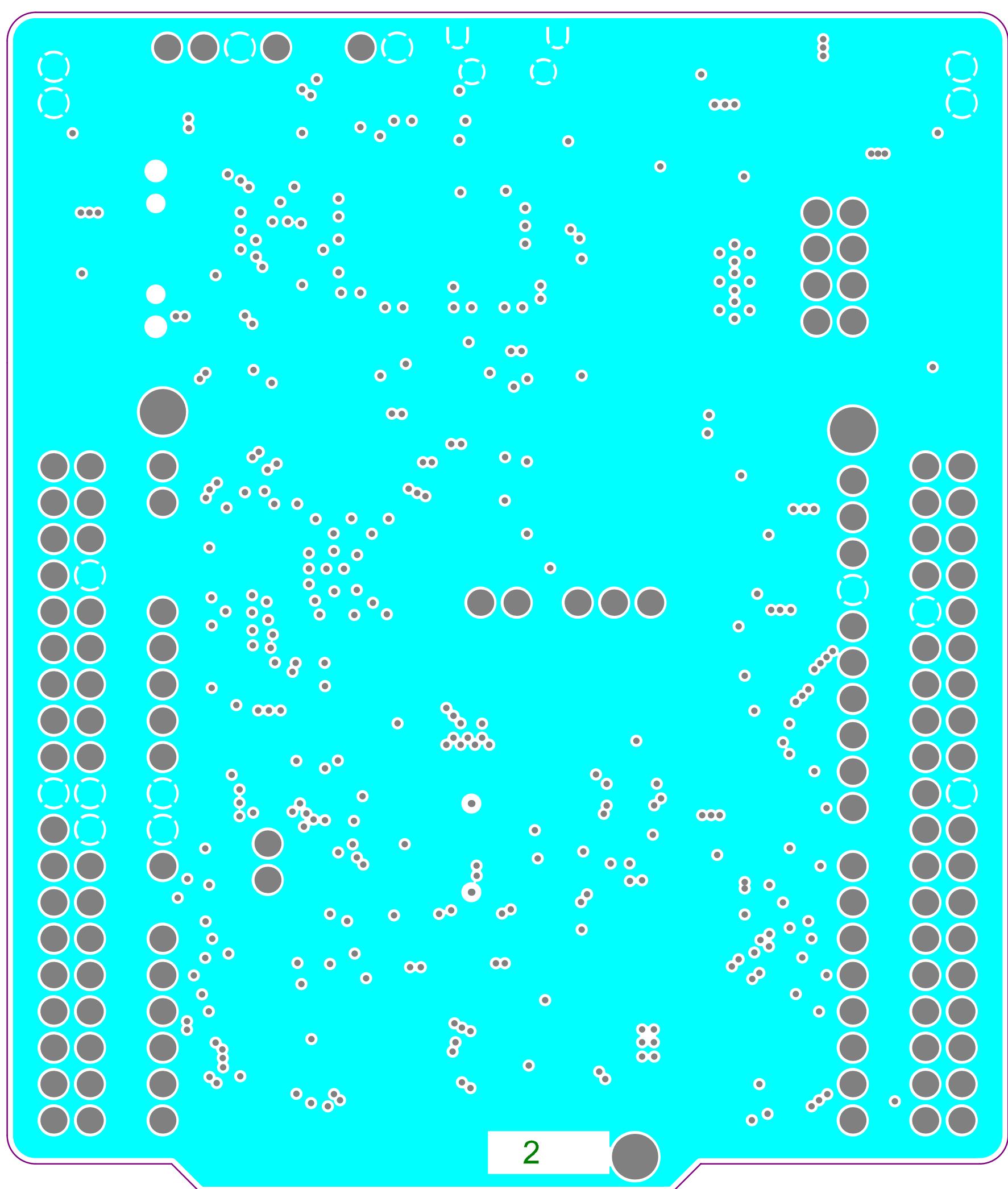
Top Solder

.GBS



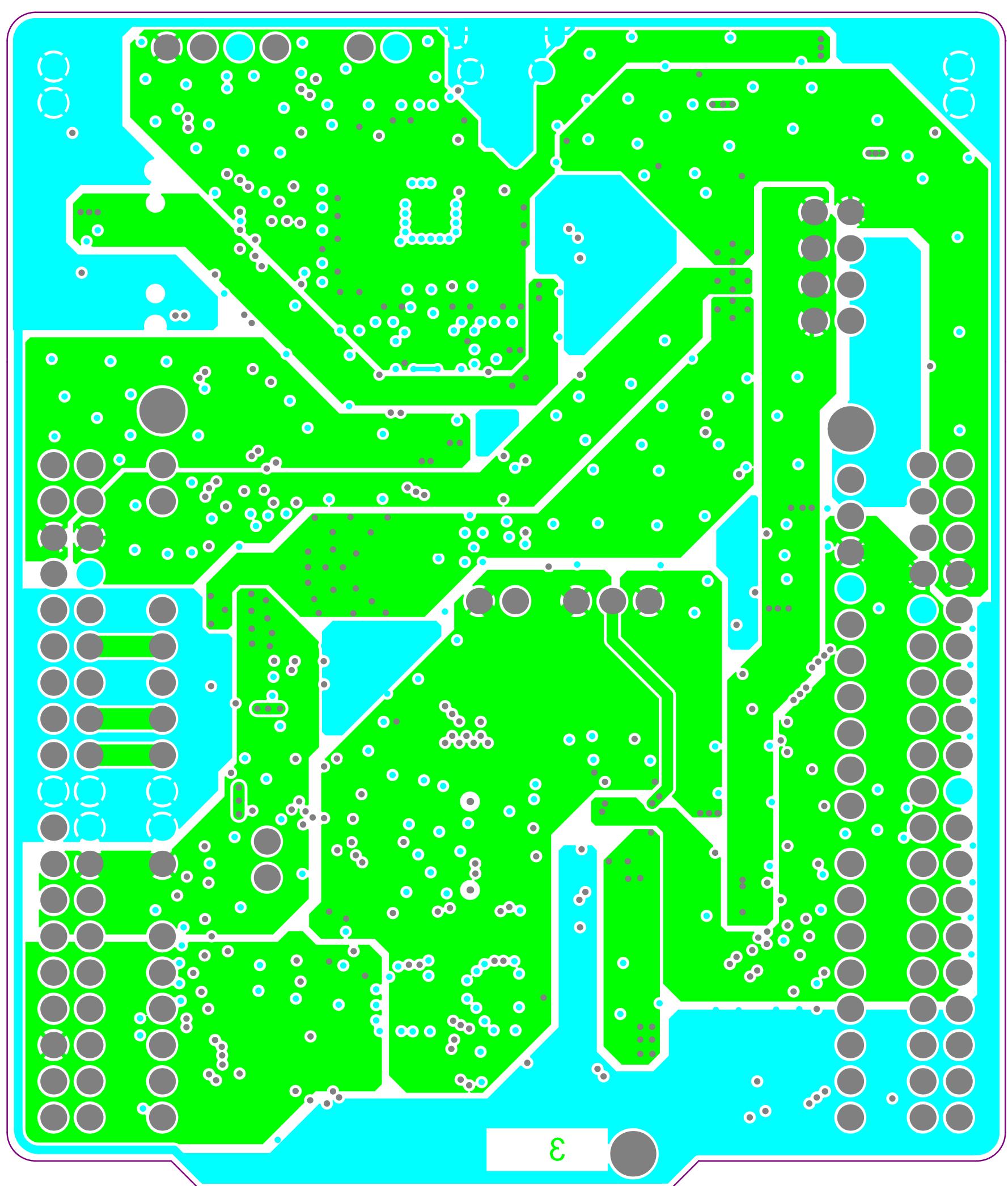
Top Layer

.GBL



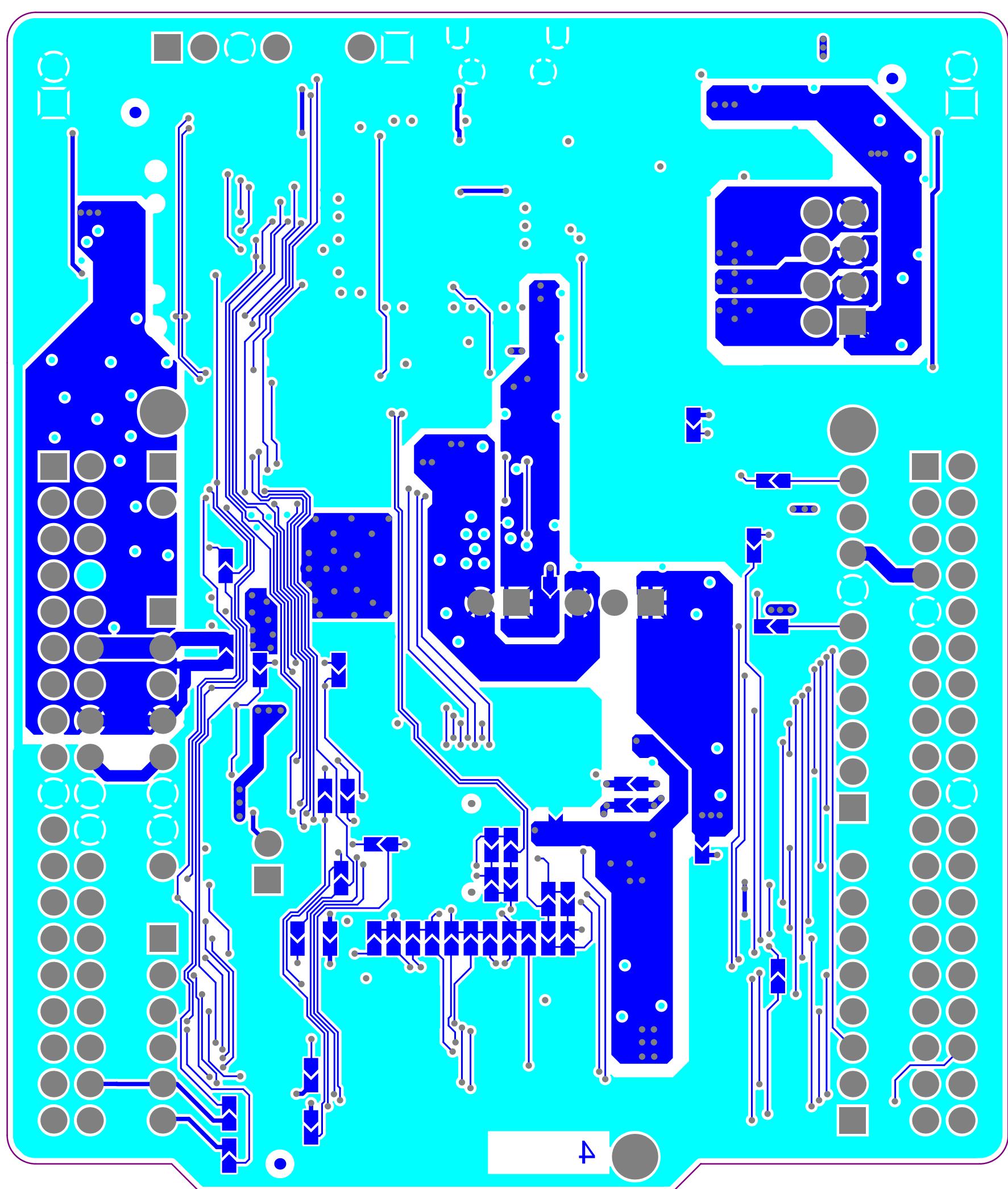
61

Signal Layer 1



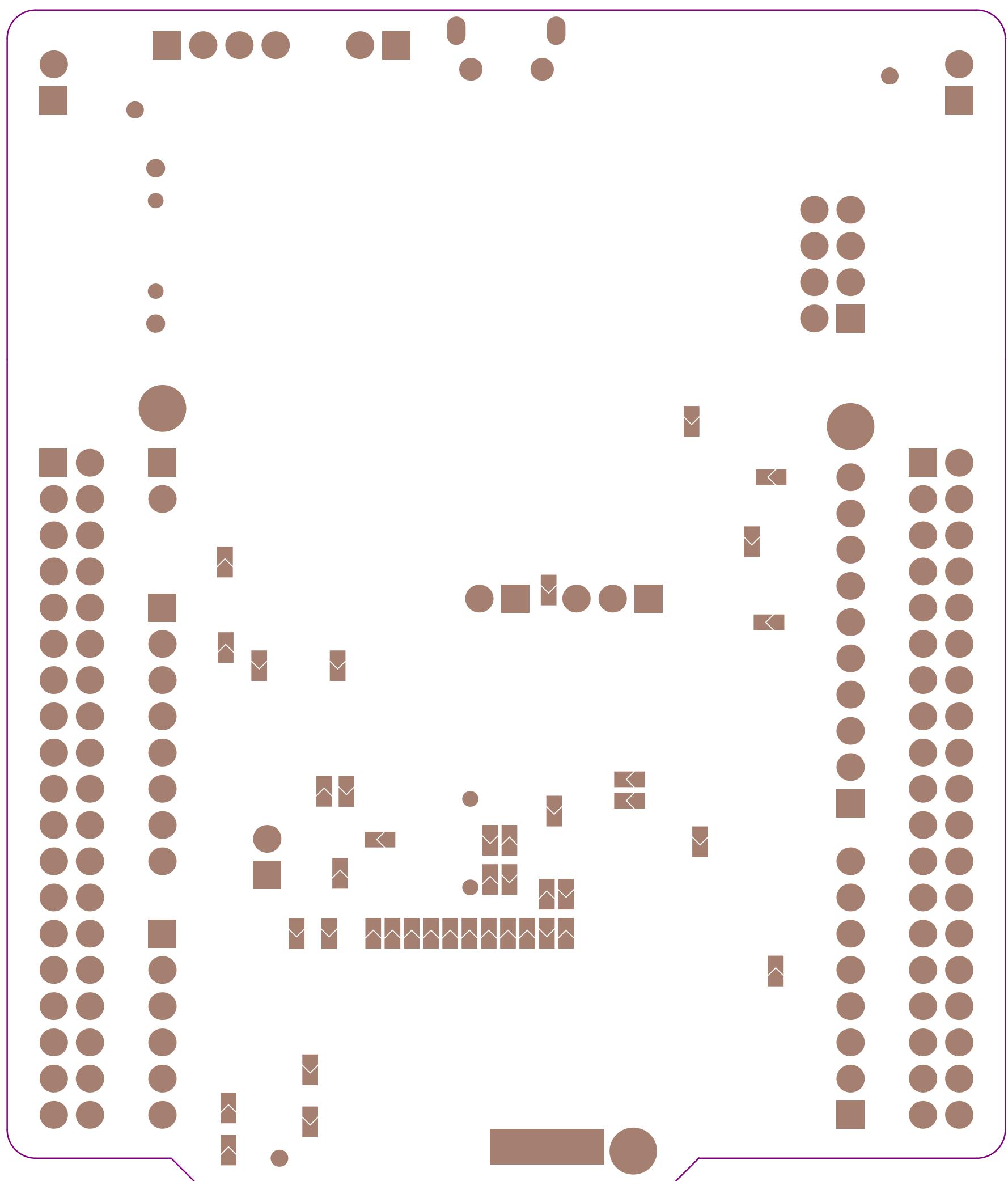
.G2

Siglent Taylor S



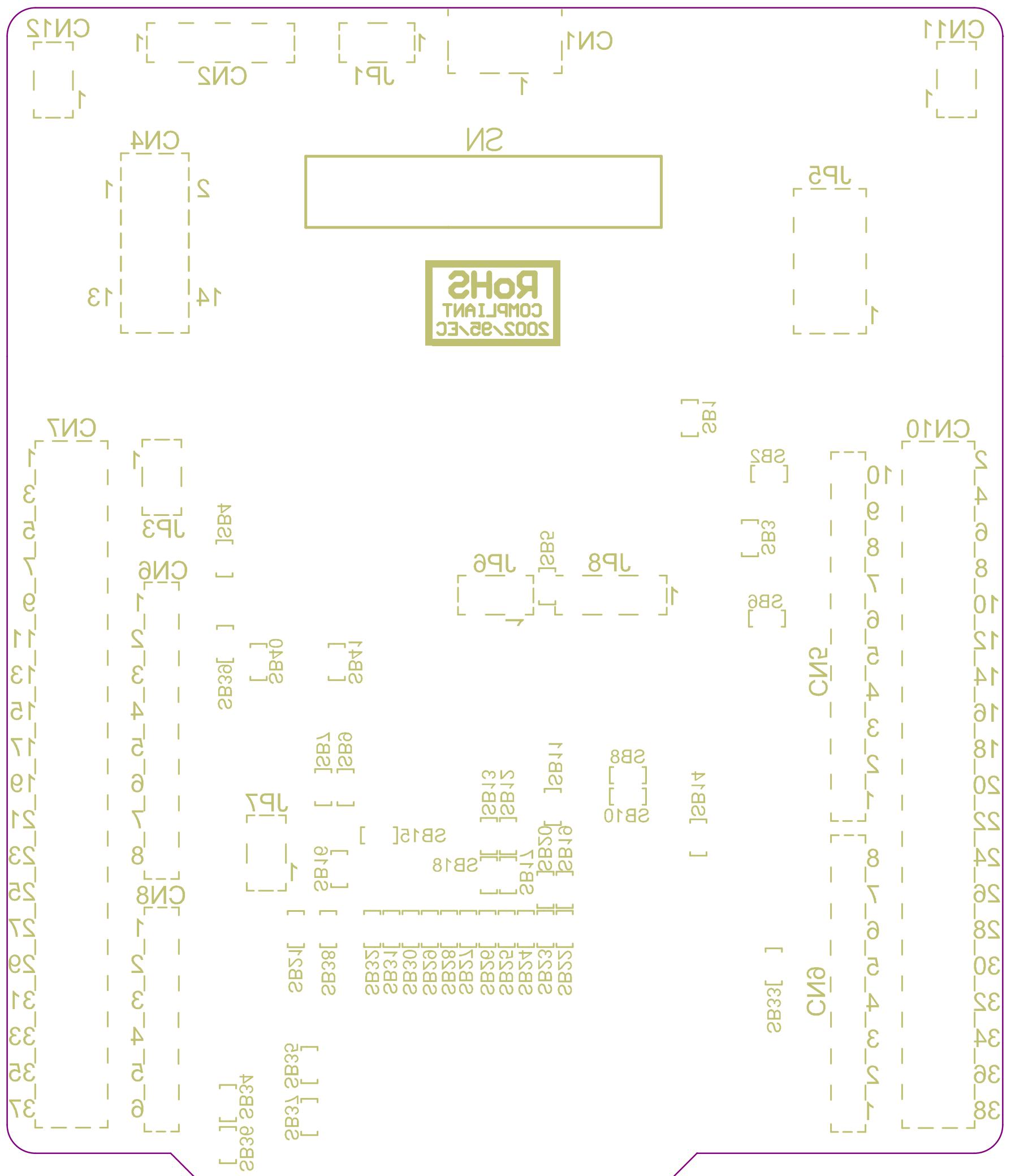
.GTL

Bottom Layer



.GTs

Bottom Solider



OT&.

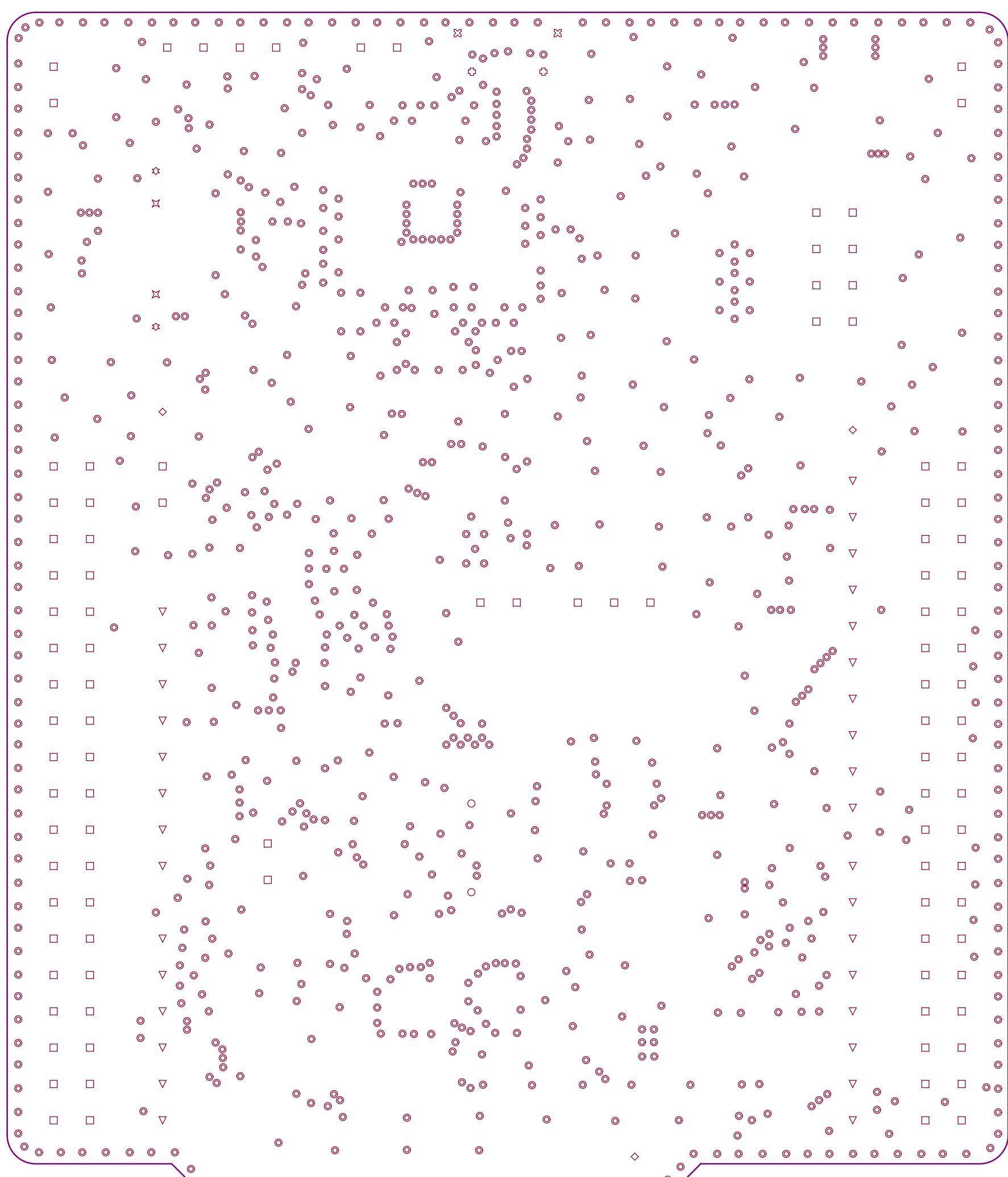
Bottow Overby

CART-1

« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE
WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

- A. MATERIAL : FR-4 TG-170 TG-150 TG-140 **Plating type :
 lead Gold
- B. MATERIAL FAMILY : N/A
- C. SOLDERMASK COLOR : GREEN WHITE RED BLACK
- D. SILKSCREEN COLOR : WHITE YELLOW BLACK Blue ink PANTONE 2955
- E. SURFACE FINISH : ENIG IMMERSION SILVER IMMERSION TIN
- F. HASL HASL (PB-FREE) GOLDEN FINGER
- G. IMPEDANCE CONTROL : NO YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- H. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
- I. STACK-UP : PLUG MATERIAL : SOLDERMASK NON-CONDUCTIVE EPOXY.
- J. SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,015mm	3,5	
3	Top Layer	Copper	0,042mm		
4	Dielectric 1	PP-IT-180A	0,106mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2	FR4	1,248mm	4,2	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3	PP-IT-180A	0,106mm	4,2	
9	Bottom Layer	Copper	0,042mm		
10	Bottom Solder	Solder Resist	0,015mm	3,5	
11	Bottom Overlay				

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.120mm
GAPS : 0.120mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
◎	920	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
✗	2	0,600mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1,300mm (51,18mil)	0,700mm (27,56mil)
✚	2	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
❖	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
○	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	103	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	32	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
❖	2	1,190mm (46,85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
◇	3	3,200mm (125,98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
1068 Total								

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

IMPEDANCE TABLE

LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	0.160	0.226	NA	90 ohm	+/- 10%

DR1

Drill Drawing